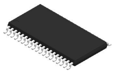
DATA BOOK
PACKAGE OUTLINE

LEADFRAME EXAMPLE
4223680

DRAFTER: K. SINCERBOX	DATE: 05/24/2017			DIMENSIONS IN MILLIMETERS			
DESIGNER:	DATE:	TEXAS INSTRUMENTS SEMICONDUCTOR OPERATIONS				CODE IDENTITY NUMBER 01295	
CHECKER: T. LEQUANG	DATE: 05/24/2017	ePOD, DAP0038E / HTSSOP 38 PIN, 0.65 MM PITCH					
ENGINEER: C. WU	DATE: 05/24/2017						
APPROVED: D. CHIN	DATE: 05/24/2017						
RELEASED: WDM	DATE: 05/24/2017						
TEMPLATE INFO: EDGE# 4218519	DATE: 04/07/2016	SCALE NTS	SIZE A	4223749	REV A	PAGE 1 OF 5	

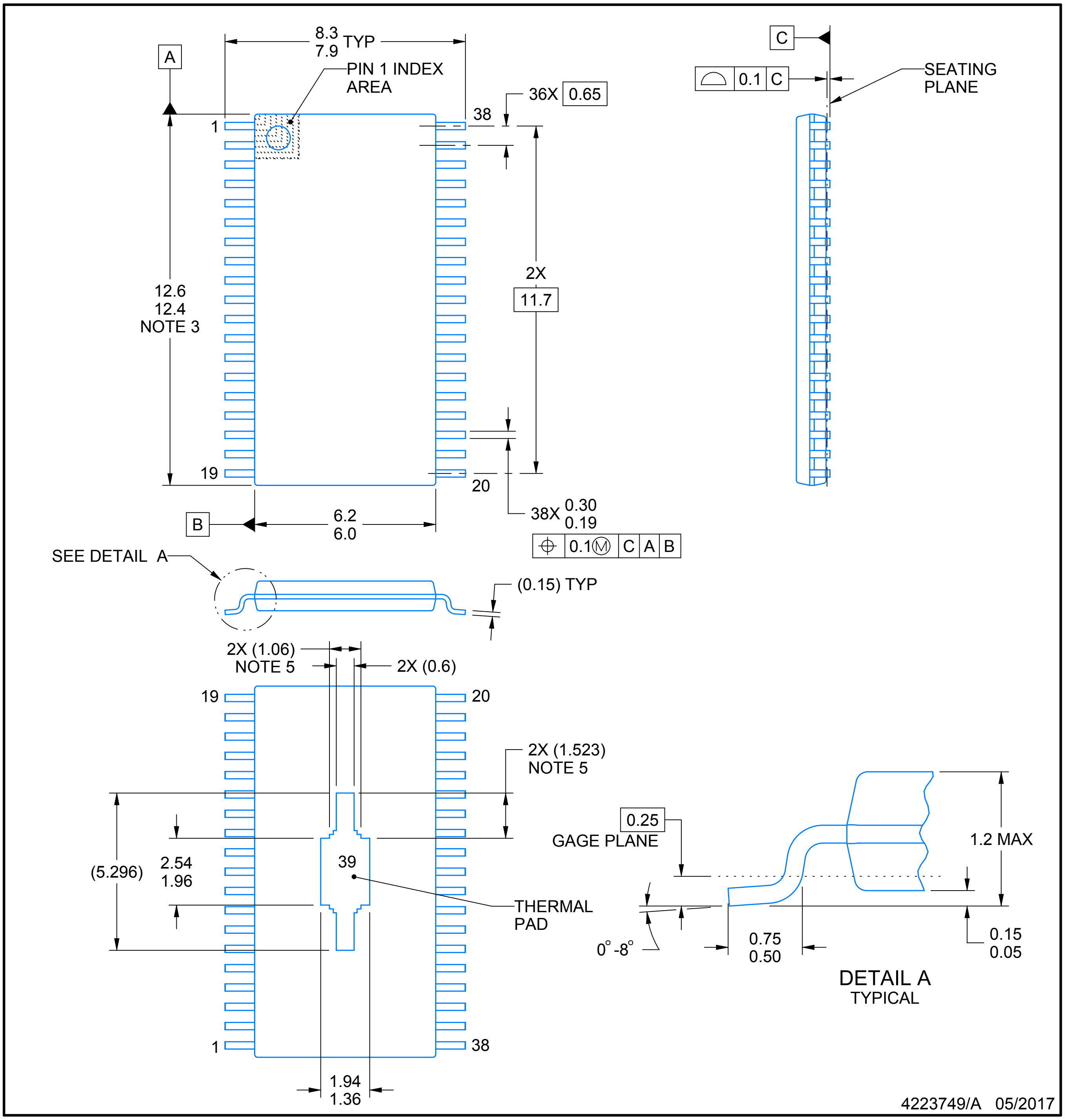
PACKAGE OUTLINE



DAP0038E

PowerPAD™ TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

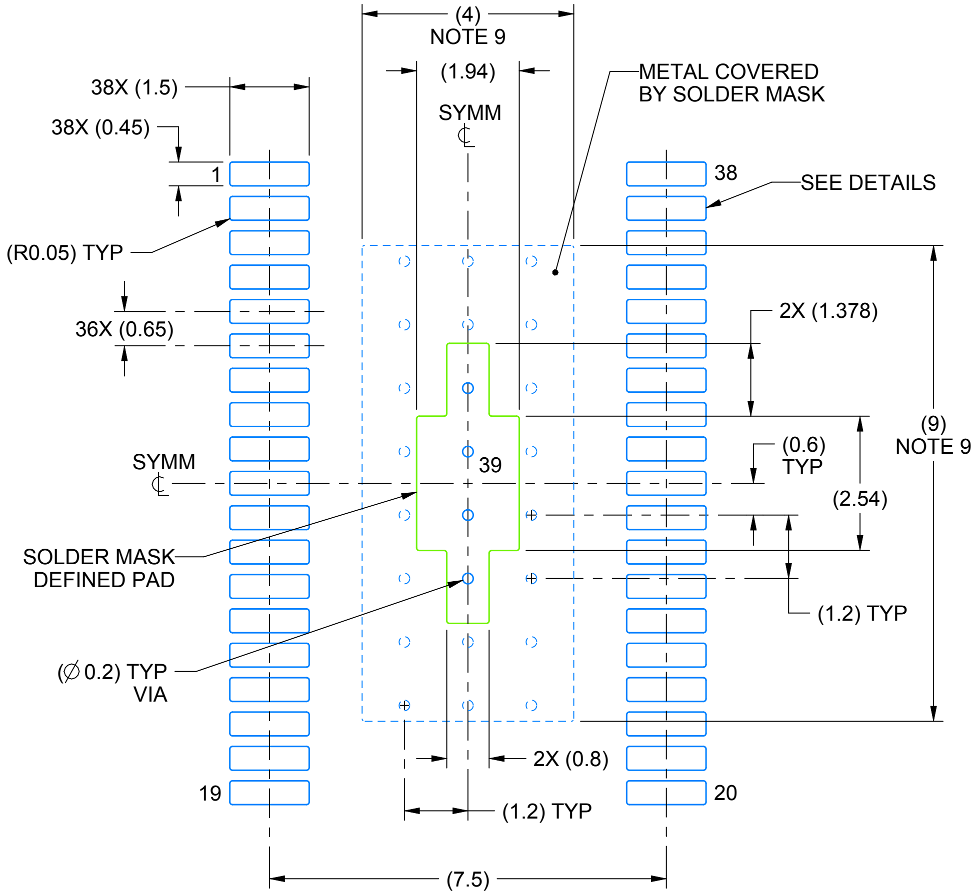


NOTES:

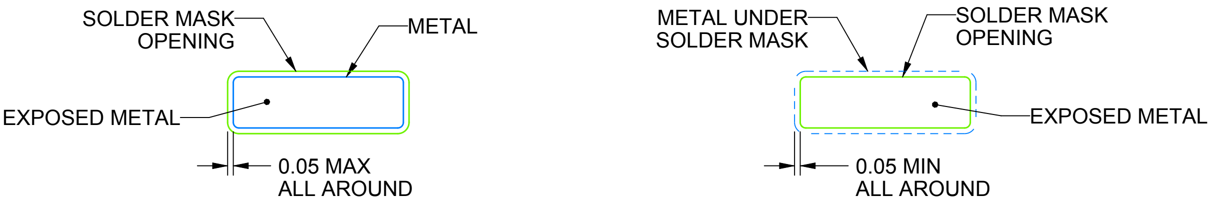
PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-153.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 7X



NON-SOLDER MASK
DEFINED

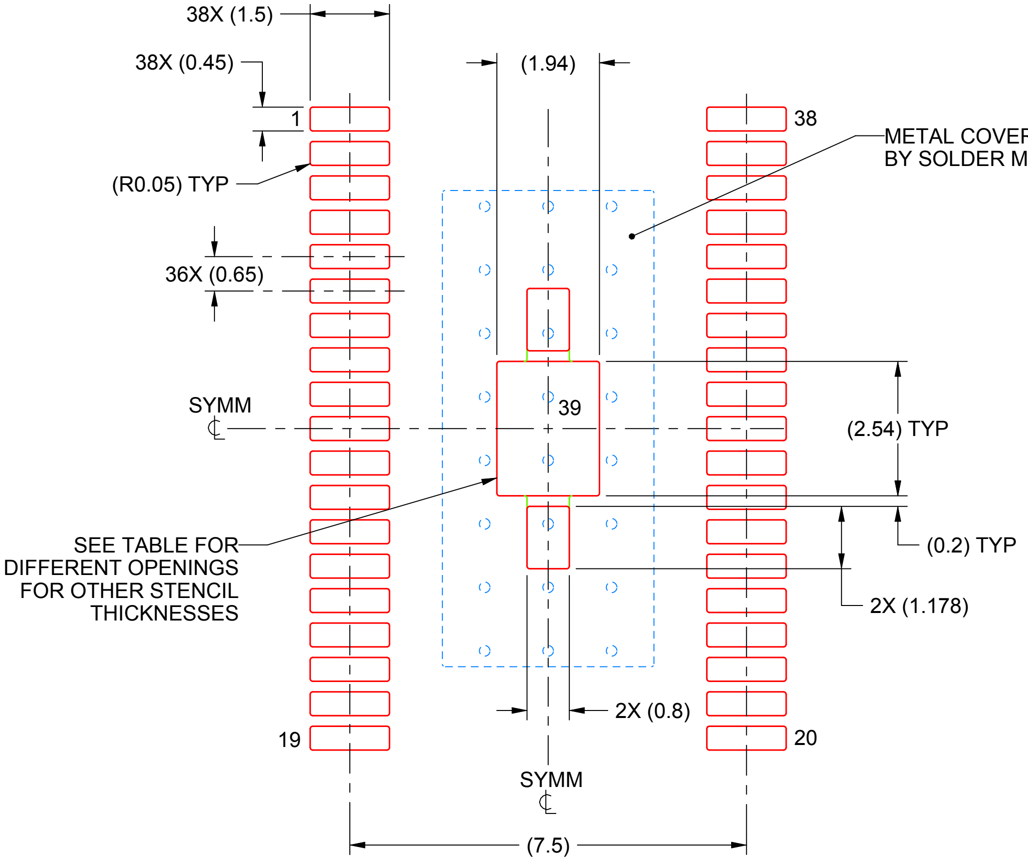
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4223749/A 05/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 7X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.17 X 2.84
0.125	1.94 X 2.54 (SHOWN)
0.15	1.77 X 2.32
0.175	1.64 X 2.15

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2165993	05/24/2017	C. WU / K. SINCERBOX

SCALE	SIZE		REV	PAGE
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